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Part Number: **0737690100**
Status: **Active**
Overview: HDM Backplane Connector System
Description: HDM Board-to-Board Stacking Header, High Rise Vertical, Press-Fit, Open End Option, 72 Circuits, Stack Height 15.05mm

Documents:

3D Model	Product Specification PS-73780-999-001 (PDF)
Drawing (PDF)	Packaging Specification PK-70873-0870-001 (PDF)
3D Model (PDF)	RoHS Certificate of Compliance (PDF)

General

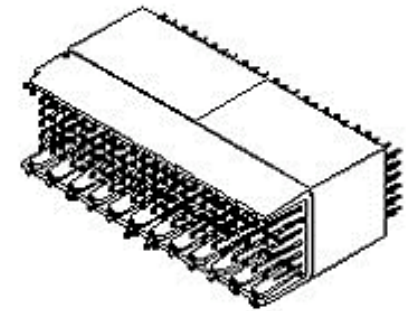
Product Family	Backplane Connectors
Series	<u>73769</u>
Application	Backplane, Mezzanine
Component Type	PCB Header
Overview	<u>HDM Backplane Connector System</u>
Product Name	HDM
UPC	800753948020

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Net Weight	12.780/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.40mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.381µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	100V AC



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Not Contained Per -
D(2020)9139-DC (19
Jan 2021)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS

ELV

RoHS Phthalates

China RoHS

Green Image

Not Relevant

Not Contained

Search Parts in this Series

73769 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description

Product #

Backplane Signal
Insertion Module
Press-In Tool for
2.00mm Pitch HDM*
Board-to-Board
Backplane Header

622008502

Solder Process Data

Lead-free Process Capability

N/A

Material Info**Reference - Drawing Numbers**

Packaging Specification

PK-70873-0870-001

Product Specification

PS-73780-999-001

Sales Drawing

SD-73769-001-001

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